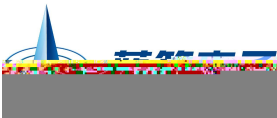
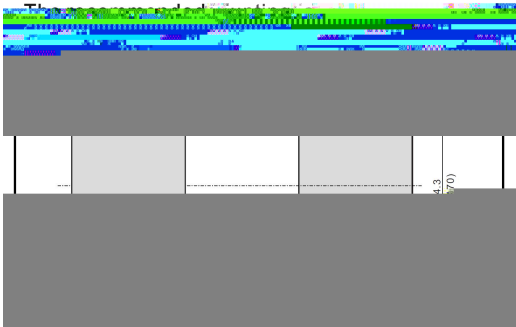
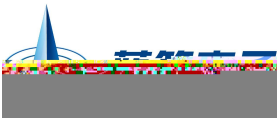


[illegible]



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, , ,





参数	参数符号	数值							单位
℃	()								
									℃
									℃



参数	参数符号	测试条件	数值						单位
		℃							
		℃							

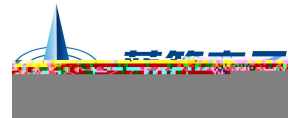
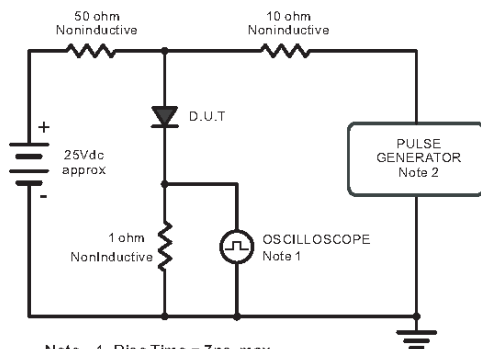


Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7 ns, max.
Input Impedance = 1 megohm, 22pF.
2. Rise Time = 10 ns, max.
Source Impedance = 50 ohms.

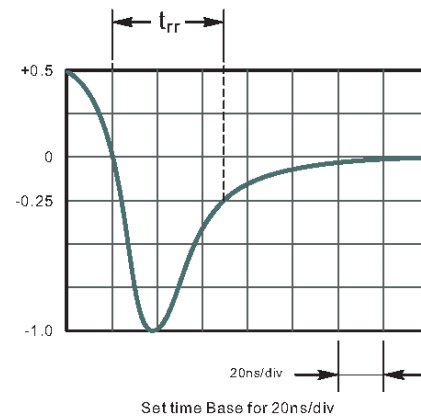


Fig.2 Maximum Average Forward Current Rating

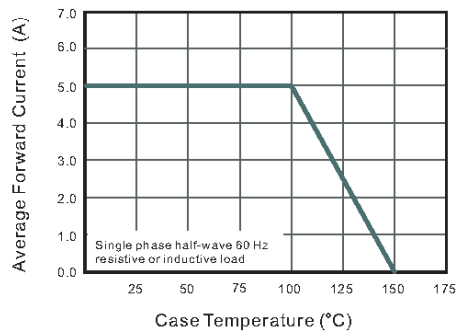


Fig.3 Typical Reverse Characteristics

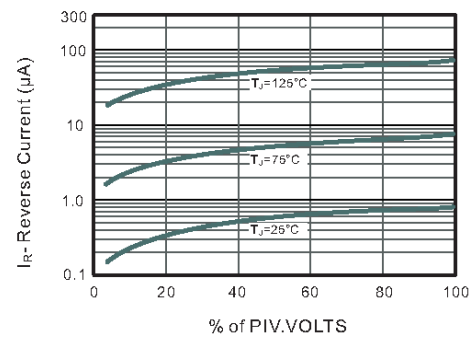


Fig.4 Typical Forward Characteristics

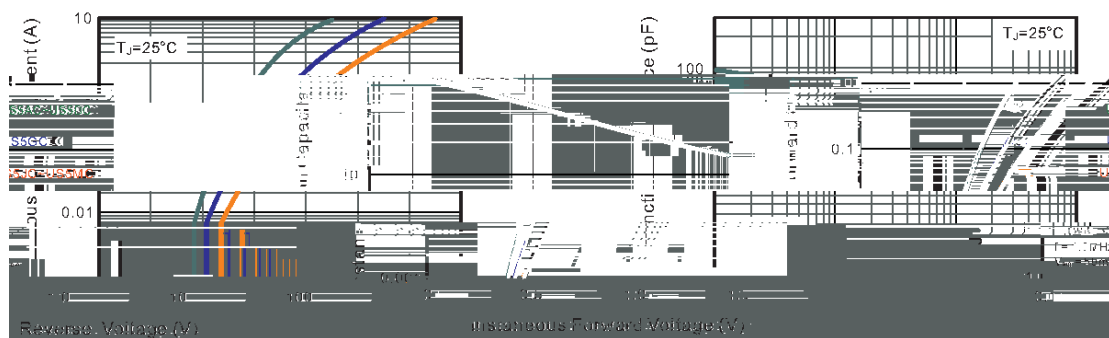
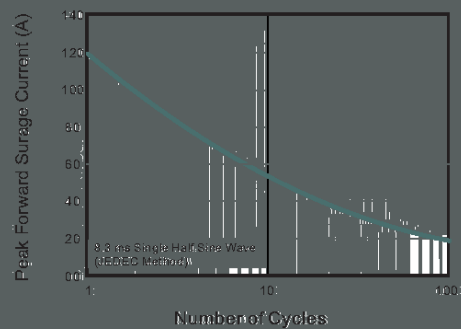
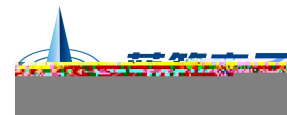


Fig.5 Typical Junction Capacitance

Fig.6 Maximum Non-Repetitive Peak Forward Surge Current

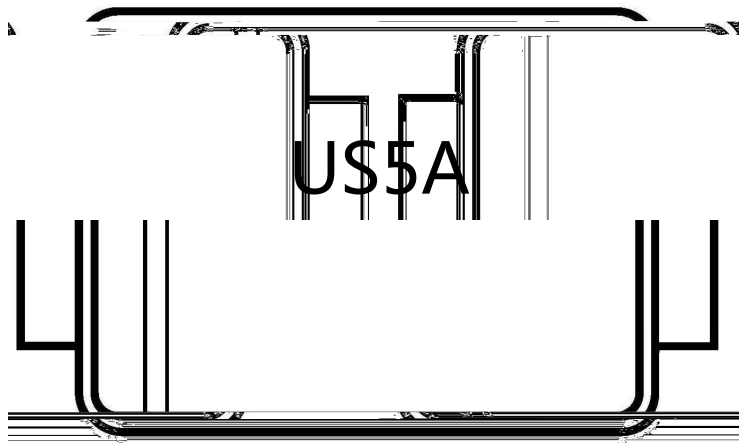
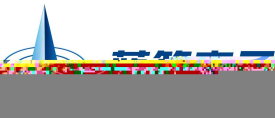


max	2.62	7.0	6.2	0.0	0.24
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Marking

Type number		Marking code	
U2a1	I	U2a1.1	I
U2a2	I	U2a2.1	I
U2a3	I	U2a3.1	I
U2a4	I	U2a4.1	I
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U2a7	I	U2a7.1	I



US5A

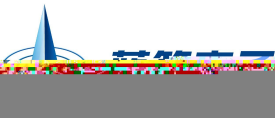
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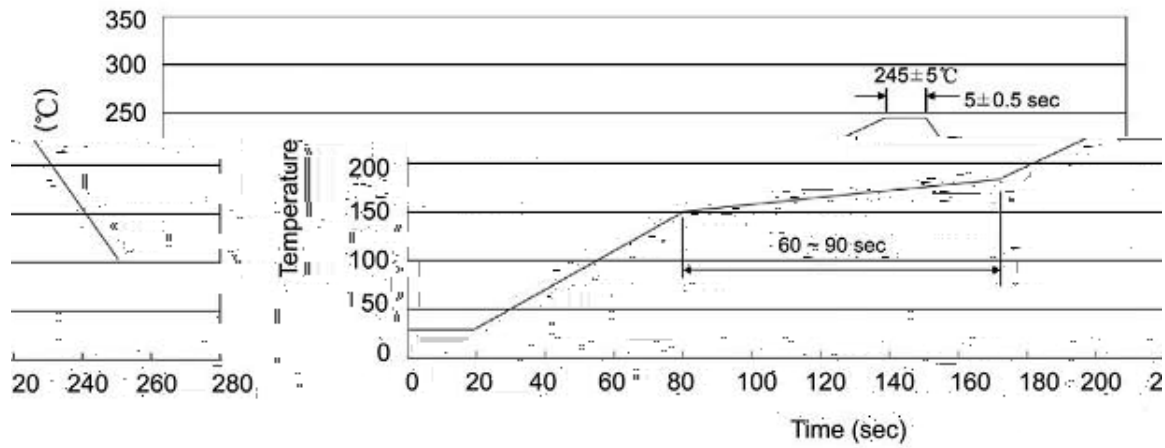
US5A

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Temperature Profile for IR Reflow Soldering(Pb-Free)



± °C

± °C

± °C

± °C

± °C

±

± °C

±

	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel "	Inner Box	Outer Box